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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/797,003	03/11/2004	Akiji Shibata	503.43552X00	3868
20457	7590 09/22/2005		EXAMINER	
	I, TERRY, STOUT & F	CHAMBLISS, ALONZO		
1300 NORTH SEVENTEENTH STREET SUITE 1800 ARLINGTON, VA 22209-3873			ART UNIT	PAPER NUMBER
			2814	

DATE MAILED: 09/22/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

	111					
	Application No.	Applicant(s)				
Office Action Comments	10/797,003	SHIBATA ET AL.				
Office Action Summary	Examiner	Art Unit				
	Alonzo Chambliss	2814				
The MAILING DATE of this communication appeared for Reply	ears on the cover sheet with the o	correspondence address				
A SHORTENED STATUTORY PERIOD FOR REPLY THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a reply - If NO period for reply is specified above, the maximum statutory period w - Failure to reply within the set or extended period for reply will, by statute, Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	6(a). In no event, however, may a reply be tir within the statutory minimum of thirty (30) day ill apply and will expire SIX (6) MONTHS from cause the application to become ABANDONE	mely filed ys will be considered timely. In the mailing date of this communication. ED (35 U.S.C. § 133).				
Status						
1) Responsive to communication(s) filed on 13 Ma	ay 2004.					
2a) ☐ This action is FINAL . 2b) ☑ This	☐ This action is FINAL. 2b) ☐ This action is non-final.					
3)☐ Since this application is in condition for allowan	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is					
closed in accordance with the practice under E.	x parte Quayle, 1935 C.D. 11, 4	53 O.G. 213.				
Disposition of Claims						
4)⊠ Claim(s) <u>1 and 2</u> is/are pending in the application.						
4a) Of the above claim(s) is/are withdrawn from consideration.						
5) Claim(s) is/are allowed.	· · ·					
6)⊠ Claim(s) <u>1 and 2</u> is/are rejected.						
	· · · · · · · · · · · · · · · · · · ·					
8) Claim(s) are subject to restriction and/or	election requirement.					
Application Papers						
9) The specification is objected to by the Examiner.						
10)⊠ The drawing(s) filed on 11 March 2004 is/are: a)□ accepted or b)⊠ objected to by the Examiner.						
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a). Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).						
11) The oath or declaration is objected to by the Exa	=	•				
	ammer. Note the attached Office	ACTION OF TOMIN PTO-152.				
Priority under 35 U.S.C. § 119						
 12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of: 1. Certified copies of the priority documents)-(d) or (f).				
2. Certified copies of the priority documents						
3. Copies of the certified copies of the priori		ed in this National Stage				
application from the International Bureau						
* See the attached detailed Office action for a list of	or the centiled copies not receive	2 0.				
Attachment(s)	_					
1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948)	4) 🔲 Interview Summary Paper No(s)/Mail Da	(PTO-413)				
3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)	5) Notice of Informal F	Patent Application (PTO-152)				
Paper No(s)/Mail Date <u>3/11/04</u> .	6)					

DETAILED ACTION

1. The amendment filed on 5/13/04 has been fully considered and made of record in the instant application.

Priority

2. Receipt is acknowledged of papers submitted under 35 U.S.C. 119(a)-(d), which papers have been placed of record in the file.

Information Disclosure Statement

3. The information disclosure statement (IDS) submitted on 3/11/04 was filed before the mailing date of the non-final rejection on 9/19/05. The submission is in compliance with the provisions of 37 CFR 1.97. Accordingly, the information disclosure statement is being considered by the examiner.

Drawings

4. Figures 9-12 should be designated by a legend such as --Prior Art-- because only that which is old is illustrated. See MPEP § 608.02(g). Corrected drawings in compliance with 37 CFR 1.121(d) are required in reply to the Office action to avoid abandonment of the application. The replacement sheet(s) should be labeled "Replacement Sheet" in the page header (as per 37 CFR 1.84(c)) so as not to obstruct any portion of the drawing figures. If the changes are not accepted by the examiner, the

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applicant will be notified and informed of any required corrective action in the next Office action. The objection to the drawings will not be held in abeyance.

Specification

5. The title of the invention is not descriptive. A new title is required that is clearly indicative of the invention to which the claims are directed. The following title is suggested: " MOLD DIE FOR A SEMICONDUCTOR DEVICE".

Claim Rejections - 35 USC § 102

6. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- 7. Claims 1 and 2 are rejected under 35 U.S.C. 102(b) as being clearly anticipated by Weber (US 6,157,086).

With respect to Claims 1 and 2, Weber teaches a mold die comprising a first die 32 having a recess of a predetermined form and a second flat die 34. The first die to be disposed on a surface of a wiring board 14 (i.e. having a conductive pattern) by the mold compound 16, wherein the wiring board 14 has a plurality of openings 26 and a semiconductor chip 12 mounted on the surface via an elastic material (i.e. solder bumps). The second die 34 is disposed on a back of the surface of the wiring board 14 on which the semiconductor chip 12 is mounted for sealing with an insulating resin 16

(i.e. by transfer mold process) a periphery of the semiconductor chip 12 and at least one of the opening 26 of the wiring board, wherein the second die 34 comprises a protrusion (i.e. about channel 38) disposed around an area overlapping the opening 26 to be sealed with the insulating resin 16 (see col. 3 lines 20-67, col. 4 lines 1 –67, and col. 6 lines 15-20; Figs. 6-8).

The prior art made of record and not relied upon is cited primarily to show the product of the instant invention.

Conclusion

8. Any inquiry concerning the communication or earlier communications from the examiner should be directed to Alonzo Chambliss whose telephone number is (571) 1927.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the Group receptionist whose telephone number is (703) 308-7956

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system Status information for published applications may be obtained from either Private PMR or Public PMR. Status information for unpublished applications is available through Private PMR only. For more information about the PMR system see http://pair-dkect.uspto.gov. Should you have questions on access to the Private PMR system contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free) or EBC_Support@uspto.gov.

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AC/September 19, 2005

Alonzo Chambliss

Primary Patent Examiner

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